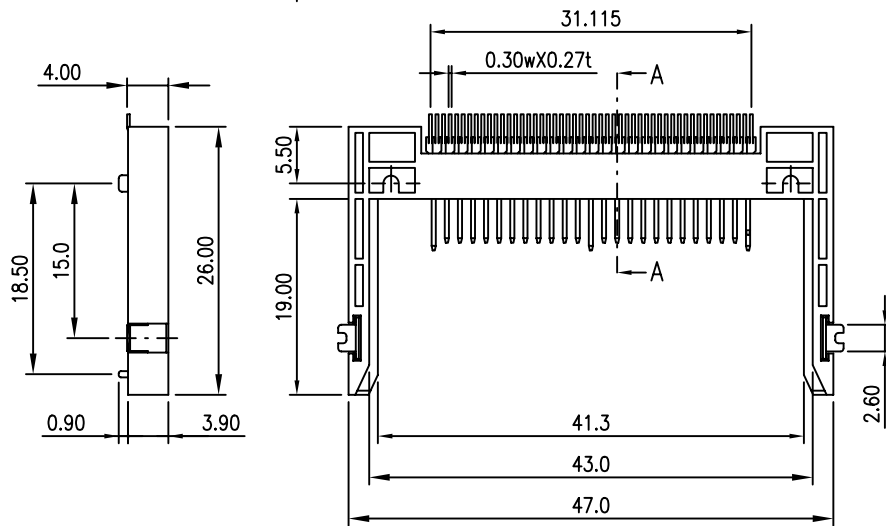
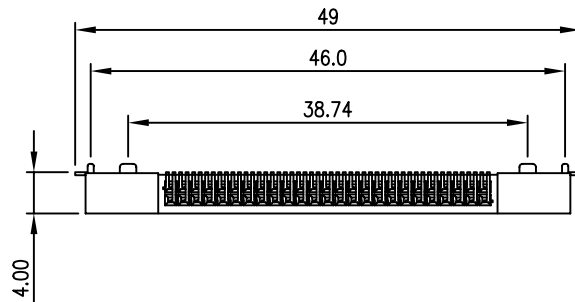
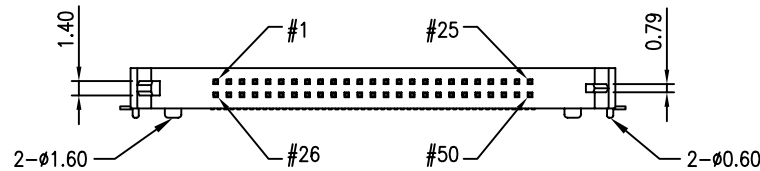
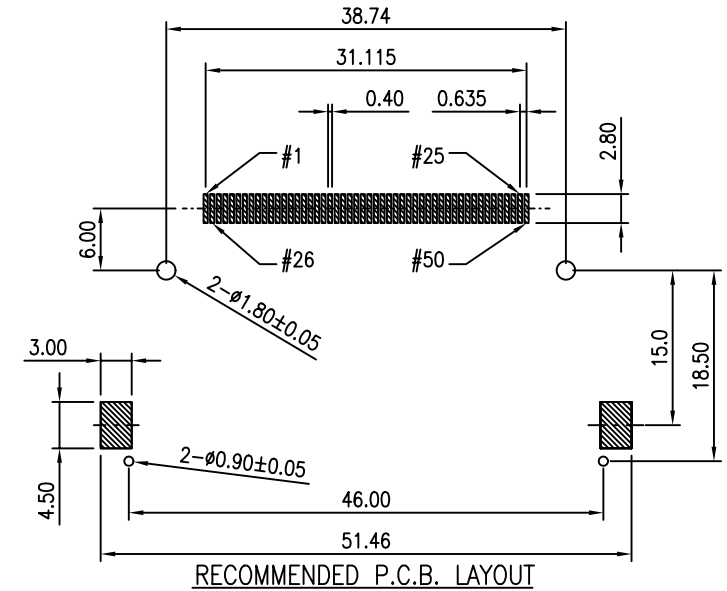


SECTION A-A



MATERIAL
 HOUSING: HIGH TEMPERATURE THERMOPLASTIC.
 CONTACT: COPPER ALLOY.
 PED: BRASS.

PLATING
 CONTACT: UNDERPLATED: 50 u" MIN Ni.
 CONTACT AREA: SELECT GOLD OVER Ni PLATED.
 SOLDER TAIL: 100 u" MIN Sn/Pb OVER Ni PLATED.
 PED: 100 u" MIN Sn/Pb OVER 50 u" MIN Ni PLATED.



RECOMMENDED P.C.B. LAYOUT

TABLE		
Pin Type	Interface Dim.	Pin No.
Detect	3.5mm (0.138In.)	25,26
General	4.25mm (0.167In.)	The others
Power	5.0mm (0.197In.)	01,13,38,50

PART NO. CFC-PW001MX3-50

DWG NO. CFC-PW001MX3-50

FILE NO. CFH-B1C0XXXXMNX

UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION



TOLERANCES ARE

X ± 0.30
 .XX ± 0.20
 .XXX ± 0.1
 AWG

DESCRIPTION: CF CARD HEADER TYPE

AREA

REVISIONS

HK

DATE